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### FDY100PZ

## Single P-Channel (– 2.5V) Specified PowerTrench® MOSFET

### **General Description**

This Single P-Channel MOSFET has been designed using Fairchild Semiconductor's advanced Power Trench process to optimize the  $R_{\text{DS(ON)}} \textcircled{Q} \ V_{\text{GS}} = -2.5v.$ 

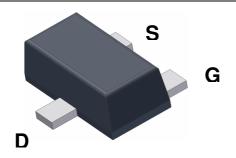
### **Applications**

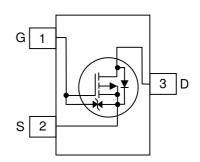
Li-Ion Battery Pack



### **Features**

- -350 mA, -20 V  $R_{DS(ON)}=1.2~\Omega$  @  $V_{GS}=-4.5$  V  $R_{DS(ON)}=1.6~\Omega$  @  $V_{GS}=-~2.5$  V
- ESD protection diode (note 3)
- RoHS Compliant





### Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Unit s
$V_{\text{DSS}}$	Drain-Source Voltage		- 20	V
$V_{GSS}$	Gate-Source Voltage		± 8	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1a)	<del>-</del> 350	mA
	– Pulsed		<b>– 1000</b>	
P <sub>D</sub>	Power Dissipation (Steady State)	(Note 1a)	625	mW
		(Note 1b)	446	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range		−55 to +150	°C

### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	200	°C/W
Rain	Thermal Resistance, Junction-to-Ambient (Note 1b)	280	

### **Package Marking and Ordering Information**

Device Marking	Device	Reel Size	Tape width	Quantity
A	FDY100PZ	7"	8mm	3000 units

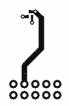
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics		I			I
BV <sub>DSS</sub>	Drain–Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = -250  \mu\text{A}$	-20			V
<u>ΔBV<sub>DSS</sub></u> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu A$ , Referenced to 25°C		15		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V},  V_{GS} = 0 \text{ V}$			-3	μΑ
$I_{GSS}$	Gate-Body Leakage,	$V_{GS} = \pm 8 \text{ V},  V_{DS} = 0 \text{ V}$			± 10	μΑ
On Char	acteristics (Note 2)					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	- 0.65	-1.0	- 1.5	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		-3		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	$\begin{array}{l} V_{GS} = -4.5 \text{ V}, \ I_D = -350 \text{ mA} \\ V_{GS} = -2.5 \text{ V}, \ I_D = -300 \text{ mA} \\ V_{GS} = -1.8 \text{ V}, \ I_D = -150 \text{ mA} \\ V_{GS} = -4.5 \text{ V}, \ I_D = -350 \text{ mA}, \\ T_J = 125^{\circ}\text{C} \end{array}$		0.5 0.8 1.3 0.7	1.2 1.6 2.7 1.6	Ω
<b>g</b> FS	Forward Transconductance	$V_{DS} = -5 \text{ V},  I_{D} = -350 \text{ mA}$		1		S
	: Characteristics	,			•	
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -10 \text{ V},  V_{GS} = 0 \text{ V},$		100		pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		30		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			15		pF
Switchin	g Characteristics (Note 2)					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = -10 \text{ V},  I_{D} = -0.5 \text{ A},$		6	12	ns
- (- )	rain on Bolay rimo			0	12	115
. ,	Turn–On Rise Time	$V_{GS} = -10 \text{ V},  I_D = -0.5 \text{ A},$ $V_{GS} = -4.5 \text{ V},  R_{GEN} = 6 \Omega$		13	23	ns
ir.	· · · · · · · · · · · · · · · · · · ·					_
d(off)	Turn-On Rise Time			13	23	ns
t <sub>r</sub> td(off)	Turn-On Rise Time Turn-Off Delay Time			13	23 16	ns ns
$t_r$ $t_{d(off)}$ $t_f$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	$V_{\text{GS}} = -4.5 \text{ V},  R_{\text{GEN}} = 6 \ \Omega$		13 8 1	23 16 2	ns ns
tr td(off) tf Qg	Turn–On Rise Time Turn–Off Delay Time Turn–Off Fall Time Total Gate Charge	$V_{GS} = -4.5 \text{ V},  R_{GEN} = 6 \ \Omega$ $V_{DS} = -10 \text{ V},  I_D = -350 \text{ mA},$		13 8 1 1.0	23 16 2	ns ns ns
$t_{r}$ $t_{d(off)}$ $t_{f}$ $Q_{g}$ $Q_{gs}$ $Q_{gd}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{GS} = -4.5 \; V,  R_{GEN} = 6 \; \Omega$ $V_{DS} = -10 \; V,  I_D = -350 \; mA,$ $V_{GS} = -4.5 \; V$		13 8 1 1.0 0.2	23 16 2	ns ns ns nC
$t_{r}$ $t_{d(off)}$ $t_{f}$ $Q_{g}$ $Q_{gs}$ $Q_{gd}$	Turn–On Rise Time Turn–Off Delay Time Turn–Off Fall Time Total Gate Charge Gate–Source Charge	$V_{GS} = -4.5 \; V,  R_{GEN} = 6 \; \Omega$ $V_{DS} = -10 \; V,  I_D = -350 \; mA,$ $V_{GS} = -4.5 \; V$		13 8 1 1.0 0.2	23 16 2	ns ns ns nC
$t_r$ $t_{d(off)}$ $t_t$ $Q_g$ $Q_{gs}$ $Q_{gd}$ Drain—So	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge Durce Diode Characteristics Drain-Source Diode Forward	$V_{GS} = -4.5 \text{ V},  R_{GEN} = 6 \ \Omega$ $V_{DS} = -10 \text{ V},  I_D = -350 \text{ mA},$ $V_{GS} = -4.5 \text{ V}$ and Maximum Ratings		13 8 1 1.0 0.2 0.3	23 16 2 1.4	ns ns ns nC nC

### Notes:

<sup>1.</sup>  $\widehat{R}_{\text{BJA}}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\text{BJC}}$  is guaranteed by design while  $R_{\text{BCA}}$  is determined by the user's board design.



200 °C/W when mounted on a 1in<sup>2</sup> pad of 2 oz copper



- b) 280 °C/W when mounted on a minimum pad of 2 oz copper Scale 1 : 1 on letter size paper
- 2. Pulse Test: Pulse Width <  $300\mu s$ , Duty Cycle < 2.0%
- The diode connected between the gate and source serves only as protection againts ESD. No gate overvoltage rating is implied.

### **Typical Characteristics**

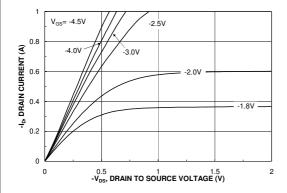


Figure 1. On-Region Characteristics.

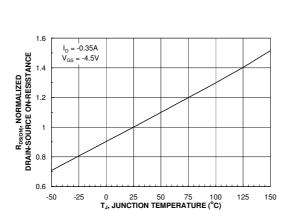


Figure 3. On-Resistance Variation with Temperature.

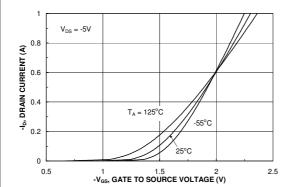


Figure 5. Transfer Characteristics.

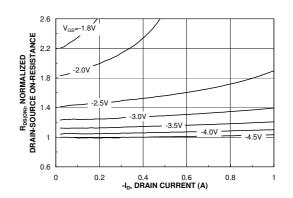


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

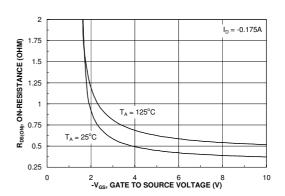


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

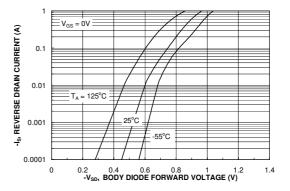


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

### **Typical Characteristics**

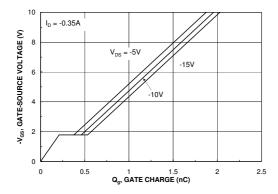


Figure 7. Gate Charge Characteristics.

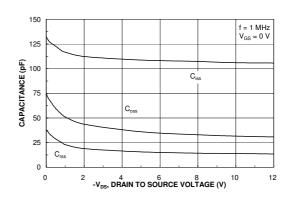


Figure 8. Capacitance Characteristics.

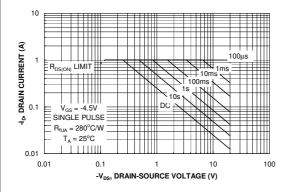


Figure 9. Maximum Safe Operating Area.

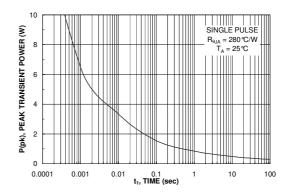


Figure 10. Single Pulse Maximum Power Dissipation.

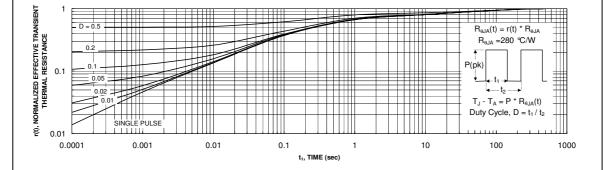
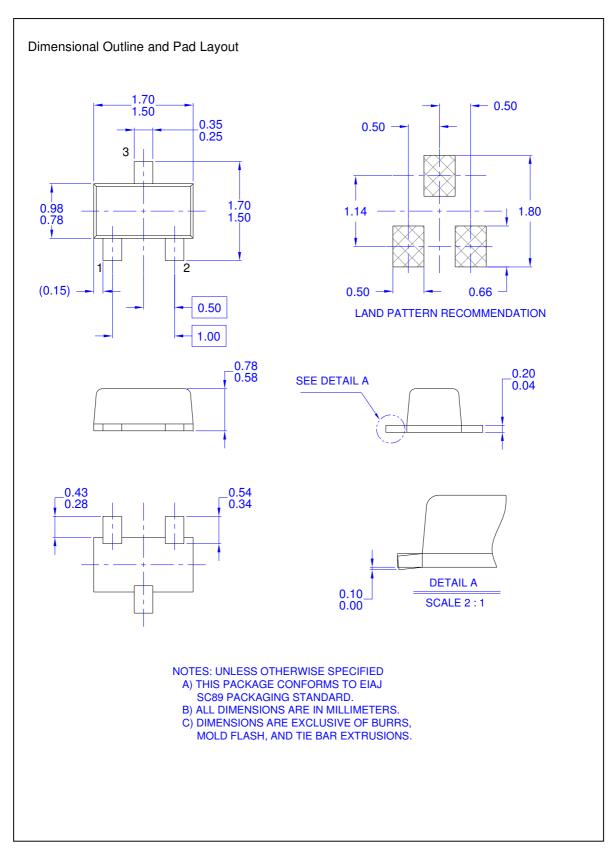


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



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